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STW77N65M5

N-channel 650 V, 0.033 Ω 69 A, MDmesh™ V Power MOSFET TO-247

Features

Order code	V _{DSS} @T _{jmax.}	R _{DS(on)} max.	I _D
STW77N65M5	710 V	< 0.038 Ω	69 A

- Higher V_{DSS} rating
- Higher dv/dt capability
- Excellent switching performance
- Easy to drive
- 100% avalanche tested

Application

Switching applications

Description

This device is a N-channel MDmesh™ V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH™ horizontal layout structure. The resulting product has extremely low onresistance, which is unmatched among siliconbased Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

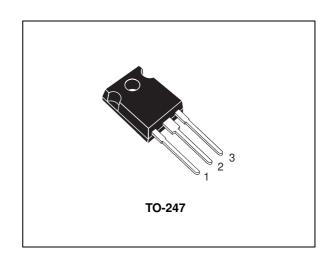


Figure 1. Internal schematic diagram

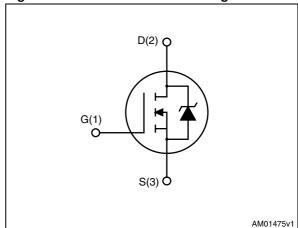


Table 1. Device summary

Order code	Marking	Package	Packaging
STW77N65M5	77N65M5	TO-247	Tube

Contents STW77N65M5

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STW77N65M5 Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{GS}	Gate- source voltage	25	V
I _D	Drain current (continuous) at T _C = 25 °C	69	Α
I _D	Drain current (continuous) at T _C = 100 °C	41.5	Α
I _{DM} ⁽¹⁾	Drain current (pulsed) 276		Α
P _{TOT}	Total dissipation at $T_C = 25 ^{\circ}C$ 400		W
I _{AR}	Max current during repetitive or single pulse avalanche (pulse width limited by T_{JMAX})	15	Α
E _{AS}	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	2000	mJ
dv/dt (2)	Peak diode recovery voltage slope 15		V/ns
T _{stg}	Storage temperature - 55 to 150		°C
T _j	Max. operating junction temperature	150	°C

^{1.} Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.31	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	50	°C/W
T _I	Maximum lead temperature for soldering purpose	300	°C

^{2.} $I_{SD} \leq 69 \text{ A}, \, \text{di/dt} = 400 \, \text{A/}\mu\text{s}, \, \text{peak V}_{DS} < V_{(BR)DSS}, \, V_{DD} = 400 \, \text{V}$

Electrical characteristics STW77N65M5

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	650			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = Max rating V_{DS} = Max rating, T_{C} =125 °C			1 100	μ Α μ Α
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 25 V			100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3	4	5	V
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 34.5 \text{ A}$		0.033	0.038	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0	-	9800 200 6	-	pF pF pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	$V_{GS} = 0$, $V_{DS} = 0$ to 520 V	-	590	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related	$V_{GS} = 0$, $V_{DS} = 0$ to 520 V	-	194	-	pF
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	1.2	-	Ω
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 520 \text{ V}, I_{D} = 34.5 \text{ A},$ $V_{GS} = 10 \text{ V}$ (see <i>Figure 16</i>)	-	185 45 65	-	nC nC nC

^{1.} $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

^{2.} $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(V)}	Voltage delay time	$V_{DD} = 400 \text{ V}, I_D = 40 \text{ A},$		160		ns
t _{r(V)}	Voltage rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$		22		ns
t _{f(i)}	Current fall time	(see Figure 17)	_	20	_	ns
t _{c(off)}	Crossing time	(see Figure 20)		40		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)		-		69 276	A A
V _{SD} (2)	Forward on voltage	I _{SD} = 69 A, V _{GS} = 0	-		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 69 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}$ $V_{DD} = 100 \text{ V (see } Figure 17)$	-	570 14 48		ns μC Α
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 69 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}$ $V_{DD} = 100 \text{ V}, T_j = 150 \text{ °C}$ (see <i>Figure 17</i>)	-	700 20 58		ns μC A

^{1.} Pulse width limited by safe operating area

^{2.} Pulsed: pulse duration = $300 \mu s$, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

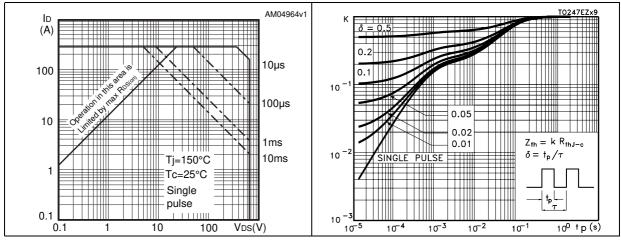


Figure 4. Output characteristics

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Figure 5. Transfer characteristics

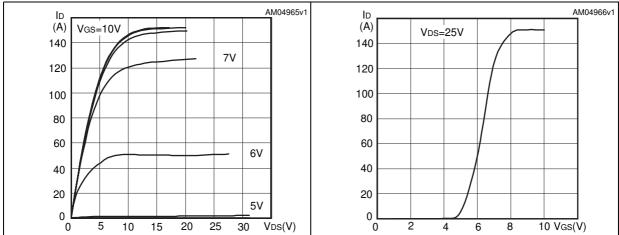


Figure 6. Gate charge vs gate-source voltage Figure 7. Static drain-source on resistance

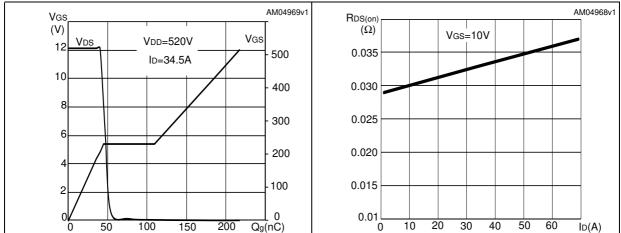


Figure 8. Capacitance variations

Figure 9. Output capacitance stored energy

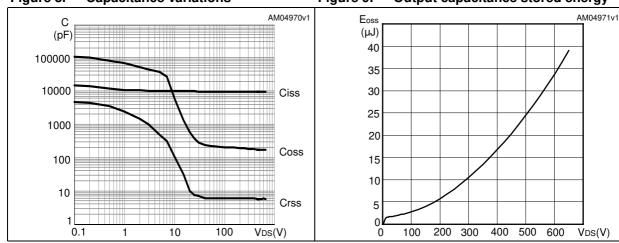


Figure 10. Normalized gate threshold voltage Figure 11. vs temperature

Figure 11. Normalized on resistance vs temperature

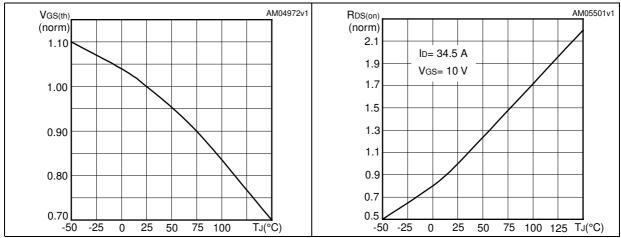
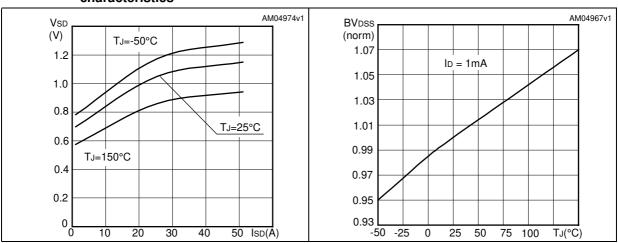


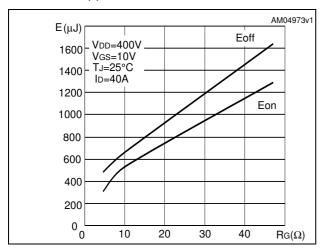
Figure 12. Source-drain diode forward characteristics

Figure 13. Normalized B_{VDSS} vs temperature



Electrical characteristics STW77N65M5

Figure 14. Switching losses vs gate resistance (1)



1. Eon including reverse recovery of a SiC diode

STW77N65M5 Test circuits

3 Test circuits

Figure 15. Switching times test circuit for resistive load

Figure 16. Gate charge test circuit

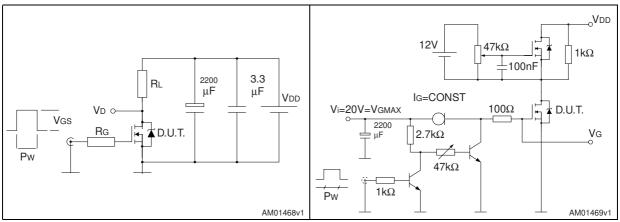


Figure 17. Test circuit for inductive load switching and diode recovery times

Figure 18. Unclamped inductive load test circuit

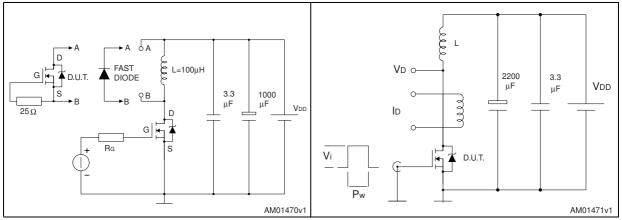
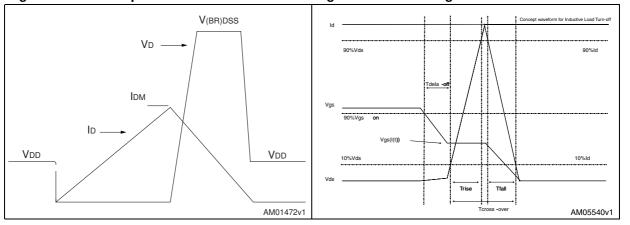


Figure 19. Unclamped inductive waveform

Figure 20. Switching time waveform



4 Package mechanical data

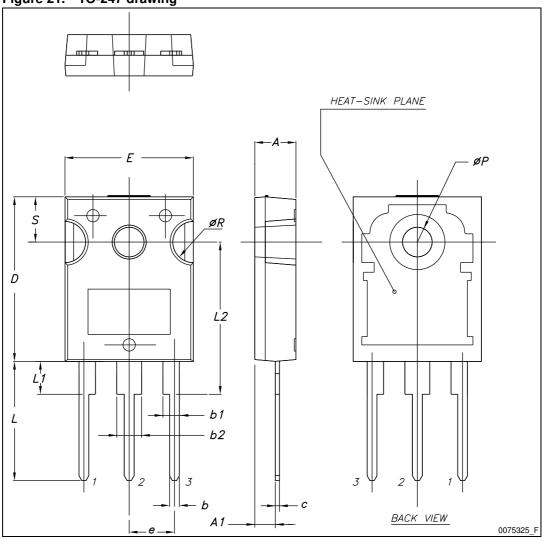
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

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Table 8. TO-247 mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
E	15.45		15.75
е		5.45	
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S		5.50	

Figure 21. TO-247 drawing



STW77N65M5 Revision history

5 Revision history

Table 9. Document revision history

Date	Revision	Changes
20-Jan-2009	1	First release.
14-Jul-2009	2	Document status promoted from preliminary data to datasheet.
03-Feb-2011	3	Section 2.1: Electrical characteristics (curves) has been updated.

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